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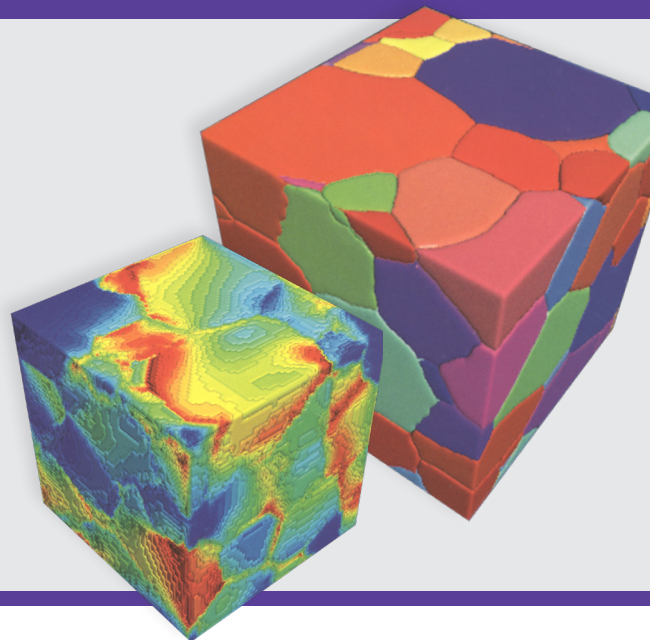
The 5th International Congress on

3DMS

3D Materials Science 2020

June 28-July 1, 2020

Hyatt Regency Washington on Capitol Hill
Washington, D.C., USA



Participate in the premier forum for 3D Materials Science by presenting at the 5th International Congress on 3D Materials Science (3DMS 2020).

The congress program includes, but is not limited to, the following technical topics:

- Methods for materials simulation, modeling, and characterization in 3D
- 3D data processing and reconstruction algorithms
- Process-microstructure-property relationships in 3D
- Materials dynamics in 3D
- Machine learning
- New characterization methods

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